

## SN74LVC162244A 16-Bit Buffer/Driver with 3-State Outputs

### 1 Features

- Member of the Texas Instruments Widebus™ Family
- Operates From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max  $t_{pd}$  of 4.4 ns at 3.3 V
- Typical  $V_{OLP}$  (Output Ground Bounce) < 0.8 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- Typical  $V_{OHV}$  (Output  $V_{OH}$  Undershoot) > 2 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V  $V_{CC}$ )
- Output Ports Have Equivalent 26  $\Omega$  Series Resistors, So No External Resistors Are Required
- $I_{off}$  Supports Live Insertion, Partial Power Down Mode, and Back Drive Protection
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 1000-V Charged-Device Model (C101)

### 2 Applications

- Motor drive
- Network switch
- Power Infrastructure
- Test and Measurement

### 3 Description

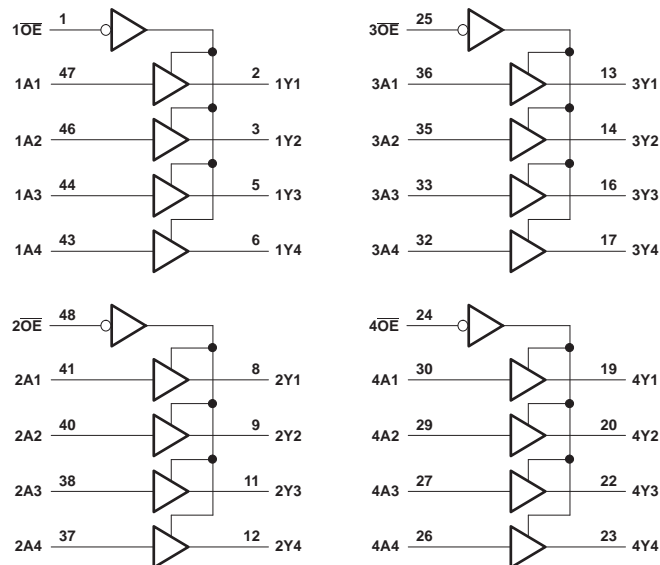
This 16-bit buffer or driver is designed for 1.65-V to 3.6-V  $V_{CC}$  operation. The device can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer.

#### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN74LVC162244A	SSOP (48)	15.88 × 7.49 mm
	TSSOP (48)	12.50 × 6.10 mm
	TVSOP (48)	9.70 × 4.40 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

### 4 Simplified Schematic



Pin numbers shown are for the DGG, DGV, and DL packages.



## Table of Contents

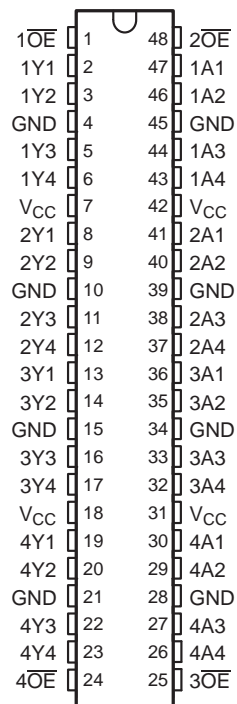
<b>1 Features</b> .....	<b>1</b>	9.1 Overview .....	11
<b>2 Applications</b> .....	<b>1</b>	9.2 Functional Block Diagram .....	11
<b>3 Description</b> .....	<b>1</b>	9.3 Feature Description .....	11
<b>4 Simplified Schematic</b> .....	<b>1</b>	9.4 Device Functional Modes .....	12
<b>5 Revision History</b> .....	<b>2</b>	<b>10 Application and Implementation</b> .....	<b>12</b>
<b>6 Pin Configuration and Functions</b> .....	<b>3</b>	10.1 Application Information .....	12
<b>7 Specifications</b> .....	<b>6</b>	10.2 Typical Application .....	12
7.1 Absolute Maximum Ratings .....	6	<b>11 Power Supply Recommendations</b> .....	<b>13</b>
7.2 Handling Ratings .....	6	<b>12 Layout</b> .....	<b>14</b>
7.3 Recommended Operating Conditions .....	7	12.1 Layout Guidelines .....	14
7.4 Thermal Information .....	7	12.2 Layout Example .....	14
7.5 Electrical Characteristics .....	8	<b>13 Device and Documentation Support</b> .....	<b>14</b>
7.6 Switching Characteristics .....	8	13.1 Trademarks .....	14
7.7 Operating Characteristics .....	8	13.2 Electrostatic Discharge Caution .....	14
7.8 Typical Characteristics .....	9	13.3 Glossary .....	14
<b>8 Parameter Measurement Information</b> .....	<b>10</b>	<b>14 Mechanical, Packaging, and Orderable Information</b> .....	<b>14</b>
<b>9 Detailed Description</b> .....	<b>11</b>		

## 5 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<b>Changes from Revision A (October 2005) to Revision B</b>	<b>Page</b>
• Updated document to new TI data sheet format .....	1
• Removed Ordering Information table .....	1
• Added Applications .....	1
• Changed MAX ambient temperature to 125°C .....	7
• Added Device and Documentation Support section .....	14
• Added ESD warning .....	14
• Added Mechanical, Packaging, and Orderable Information section .....	14

## 6 Pin Configuration and Functions

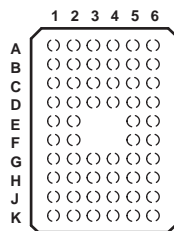
 DGG, DGV, OR DL PACKAGE  
(TOP VIEW)

**Pin Functions**

PIN		I/O	DESCRIPTION
NAME	NO.		
1OE	1	I	Output Enable 1 (input)
1Y1	2	O	1Y1 Output
1Y2	3	O	1Y2 Output
GND	4	–	Ground pin
1Y3	5	O	1Y3 Output
1Y4	6	O	1Y4 Output
V <sub>CC</sub>	7	–	Power pin
2Y1	8	O	2Y1 Output
2Y2	9	O	2Y2 Output
GND	10	–	Ground pin
2Y3	11	O	2Y3 Output
2Y4	12	O	2Y4 Output
3Y1	13	O	3Y1 Output
3Y2	14	O	3Y2 Output
GND	15	–	Ground pin
3Y3	16	O	3Y3 Output
3Y4	17	O	3Y4 Output
V <sub>CC</sub>	18	–	Power pin
4Y1	19	O	4Y1 Output
4Y2	20	O	4Y2 Output
GND	21	–	Ground pin
4Y3	22	O	4Y3 Output

**Pin Functions (continued)**

PIN		I/O	DESCRIPTION
NAME	NO.		
4Y4	23	O	4Y4 Output
4OE	24	I	Output Enable 4 (input)
3OE	25	I	Output Enable 3 (input)
4A4	26	I	4A4 Input
4A3	27	I	4A3 Input
GND	28	–	Ground pin
4A2	29	I	4A2 Input
4A1	30	I	4A1 Input
V <sub>CC</sub>	31	–	Power pin
3A4	32	I	3A4 Input
3A3	33	I	3A3 Input
GND	34	–	Ground pin
3A2	35	I	3A2 Input
3A1	36	I	3A1 Input
2A4	37	I	2A4 Input
2A3	38	I	2A3 Input
GND	39	–	Ground pin
2A2	40	I	2A2 Input
2A1	41	I	2A1 Input
V <sub>CC</sub>	42	–	Power pin
1A4	43	I	1A4 Input
1A3	44	I	1A3 Input
GND	45	–	Ground pin
1A2	46	I	1A2 Input
1A1	47	I	1A1 Input
2OE	48	I	Output Enable 2 (Input)

**GQL OR ZQL PACKAGE  
(TOP VIEW)**

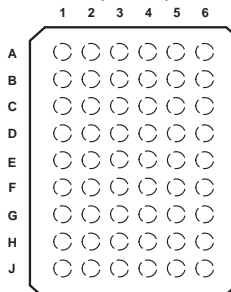


**Table 1. 3Pin Assignments<sup>(1)</sup>  
(56-Ball GQL or ZQL Package)**

	1	2	3	4	5	6
<b>A</b>	1 $\overline{OE}$	NC	NC	NC	NC	2 $\overline{OE}$
<b>B</b>	1Y2	1Y1	GND	GND	1A1	1A2
<b>C</b>	1Y4	1Y3	V <sub>CC</sub>	V <sub>CC</sub>	1A3	1A4
<b>D</b>	2Y2	2Y1	GND	GND	2A1	2A2
<b>E</b>	2Y4	2Y3			2A3	2A4
<b>F</b>	3Y1	3Y2			3A2	3A1
<b>G</b>	3Y3	3Y4	GND	GND	3A4	3A3
<b>H</b>	4Y1	4Y2	V <sub>CC</sub>	V <sub>CC</sub>	4A2	4A1
<b>J</b>	4Y3	4Y4	GND	GND	4A4	4A3
<b>K</b>	4 $\overline{OE}$	NC	NC	NC	NC	3 $\overline{OE}$

(1) NC - No internal connection

**GRD OR ZRD PACKAGE  
(TOP VIEW)**



**Table 2. Pin Assignments<sup>(1)</sup>  
(54-Ball GRD or ZRD Package)**

	1	2	3	4	5	6
<b>A</b>	1Y1	NC	1 $\overline{OE}$	2 $\overline{OE}$	NC	1A1
<b>B</b>	1Y3	1Y2	NC	NC	1A2	1A3
<b>C</b>	2Y1	1Y4	V <sub>CC</sub>	V <sub>CC</sub>	1A4	2A1
<b>D</b>	2Y3	2Y2	GND	GND	2A2	2A3
<b>E</b>	3Y1	2Y4	GND	GND	2A4	3A1
<b>F</b>	3Y3	3Y2	GND	GND	3A2	3A3
<b>G</b>	4Y1	3Y4	V <sub>CC</sub>	V <sub>CC</sub>	3A4	4A1
<b>H</b>	4Y3	4Y2	NC	NC	4A2	4A3
<b>J</b>	4Y4	NC	4 $\overline{OE}$	3 $\overline{OE}$	NC	4A4

(1) NC - No internal connection

## 7 Specifications

### 7.1 Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range	–0.5	6.5	V
V <sub>I</sub>	Input voltage range <sup>(2)</sup>	–0.5	6.5	V
V <sub>O</sub>	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	–0.5	6.5	V
V <sub>O</sub>	Voltage range applied to any output in the high or low state <sup>(2)(3)</sup>	–0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0		–50 mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		–50 mA
I <sub>O</sub>	Continuous output current			±50 mA
Continuous current through each V <sub>CC</sub> or GND				±100 mA

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V<sub>CC</sub> is provided in the *Recommended Operating Conditions* table.

### 7.2 Handling Ratings

		MIN	MAX	UNIT
T <sub>stg</sub>	Storage temperature range	–65	150	°C
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>		V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>		
		0	2000	
		0	1000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 7.3 Recommended Operating Conditions

 over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage	Operating	1.65	3.6	V
		Data retention only	1.5		
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>		V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.7		
		V <sub>CC</sub> = 2.7 V to 3.6 V	2		
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V		0.35 × V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.3 V to 2.7 V		0.7	
		V <sub>CC</sub> = 2.7 V to 3.6 V		0.8	
V <sub>I</sub>	Input voltage	0	5.5	V	
V <sub>O</sub>	Output voltage	High or low state	0	V <sub>CC</sub>	V
		High-impedance state	0	5.5	
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 1.65 V		-2	mA
		V <sub>CC</sub> = 2.3 V		-4	
		V <sub>CC</sub> = 2.7 V		-8	
		V <sub>CC</sub> = 3 V		-12	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 1.65 V		2	mA
		V <sub>CC</sub> = 2.3 V		4	
		V <sub>CC</sub> = 2.7 V		8	
		V <sub>CC</sub> = 3 V		12	
Δt/Δv	Input transition rise or fall rate			10	ns/V
T <sub>A</sub>	Operating free-air temperature	-40	125		°C

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

### 7.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		DGG	DGV	DL	UNIT
		48 PINS	48 PINS	48 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	64.3	78.4	68.4	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	17.6	30.7	34.7	
R <sub>θJB</sub>	Junction-to-board thermal resistance	31.5	41.8	41.0	
Ψ <sub>JT</sub>	Junction-to-top characterization parameter	1.1	3.8	12.3	
Ψ <sub>JB</sub>	Junction-to-board characterization parameter	31.2	41.3	40.4	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

## 7.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT	
V <sub>OH</sub>	I <sub>OH</sub> = –100 μA	1.65 V to 3.6 V	V <sub>CC</sub> – 0.2			V	
	I <sub>OH</sub> = –2 mA	1.65 V	1.2				
	I <sub>OH</sub> = –4 mA	2.3 V	1.7				
		2.7 V	2.2				
	I <sub>OH</sub> = –6 mA	3 V	2.4				
	I <sub>OH</sub> = –8 mA	2.7 V	2				
V <sub>OL</sub>	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V	0.2			V	
	I <sub>OL</sub> = 2 mA	1.65 V	0.45				
	I <sub>OL</sub> = 4 mA	2.3 V	0.7				
		2.7 V	0.4				
	I <sub>OL</sub> = 6 mA	3 V	0.55				
	I <sub>OL</sub> = 8 mA	2.7 V	0.6				
	I <sub>OL</sub> = 12 mA	3 V	0.8				
I <sub>I</sub>	V <sub>I</sub> = 0 to 5.5 V	3.6 V	±5			μA	
I <sub>off</sub>	V <sub>I</sub> or V <sub>O</sub> = 5.5 V	0	±10			μA	
I <sub>OZ</sub>	V <sub>O</sub> = 0 to 5.5 V	3.6 V	±10			μA	
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.6 V	I <sub>O</sub> = 0			20	μA
	3.6 V ≤ V <sub>I</sub> ≤ 5.5 V <sup>(2)</sup>					20	
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> – 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V	500			μA	
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V	5.5			pF	
C <sub>o</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	3.3 V	6			pF	

 (1) All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

(2) This applies in the disabled state only.

## 7.6 Switching Characteristics

 over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 3](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 1.8 V ± 0.15 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A	Y	1.5	6	1	4.3	1	5.6	1.1	4.4	ns
t <sub>en</sub>	$\overline{OE}$	Y	1.5	7.3	1	5	1	6.9	1	5.5	ns
t <sub>dis</sub>	$\overline{OE}$	Y	1.5	8.9	1	5.5	1	6.8	1.8	6.3	ns

## 7.7 Operating Characteristics

 T<sub>A</sub> = 25°C

PARAMETER	TEST CONDITIONS	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> = 3.3 V	UNIT	
		TYP	TYP	TYP		
C <sub>pd</sub> Power dissipation capacitance per buffer/driver	Outputs enabled	f = 10 MHz	31	33	35	pF
	Outputs disabled		2	3	4	



## 7.8 Typical Characteristics

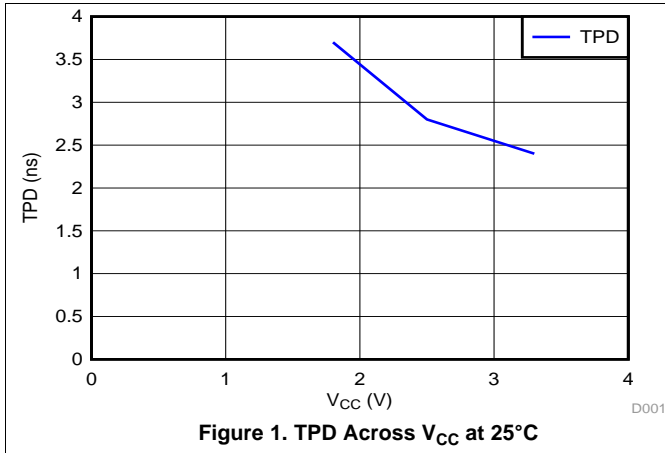


Figure 1. TPD Across V<sub>CC</sub> at 25°C

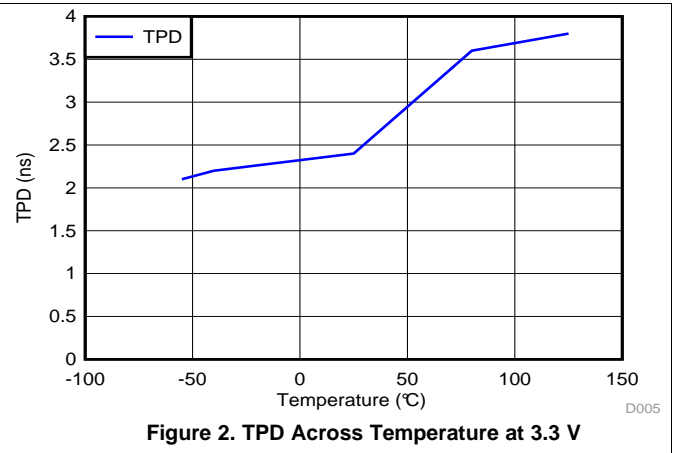
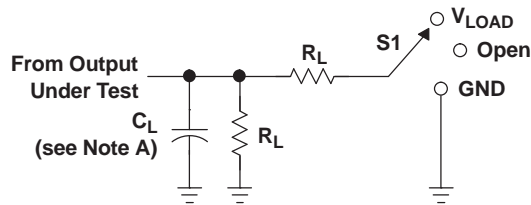


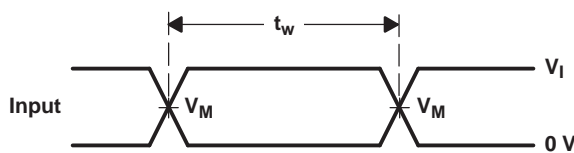
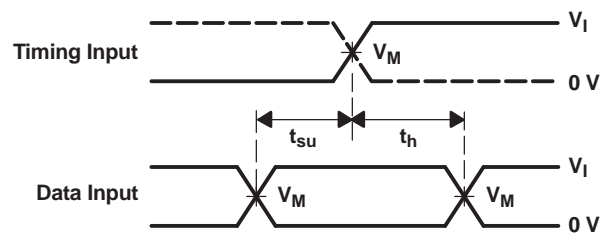
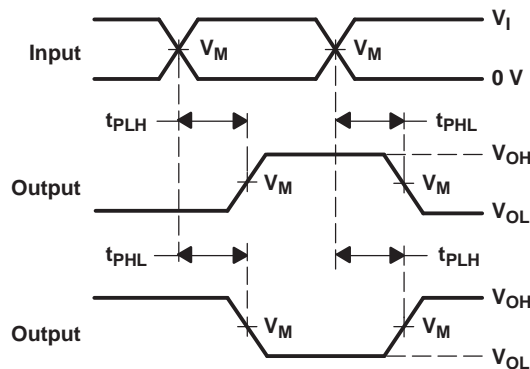
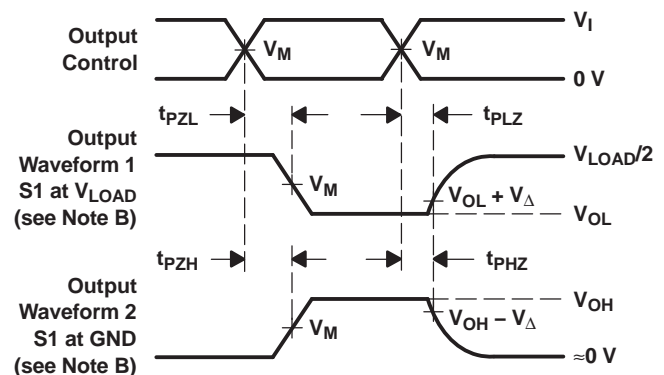
Figure 2. TPD Across Temperature at 3.3 V

## 8 Parameter Measurement Information


**LOAD CIRCUIT**

TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
$1.8\text{ V} \pm 0.15\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k $\Omega$	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V
2.7 V	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
$3.3\text{ V} \pm 0.3\text{ V}$	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V


**VOLTAGE WAVEFORMS  
PULSE DURATION**

**VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES**

**VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS**

**VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING**

- NOTES:
- $C_L$  includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ .
  - The outputs are measured one at a time, with one transition per measurement.
  - $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - All parameters and waveforms are not applicable to all devices.

**Figure 3. Load Circuit and Voltage Waveforms**

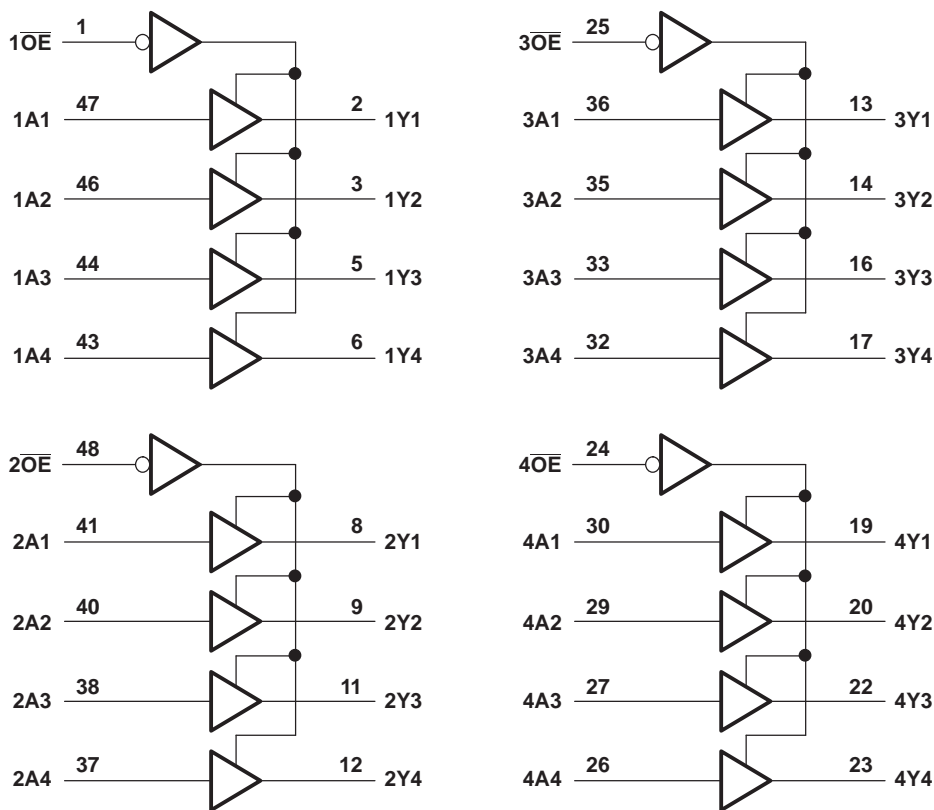
## 9 Detailed Description

### 9.1 Overview

This 16-bit buffer/driver is designed for 1.65-V to 3.6-V  $V_{CC}$  operation. The SN74LVC162244A is designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The device can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. It provides true outputs and symmetrical active-low output-enable ( $\overline{OE}$ ) inputs.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment. The outputs, which are designed to sink up to 12 mA, include equivalent 26- $\Omega$  resistors to reduce overshoot and undershoot. Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment. This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

### 9.2 Functional Block Diagram



Pin numbers shown are for the DGG, DGV, and DL packages.

### 9.3 Feature Description

- Wide operating voltage range
  - Operates from 1.65 V to 3.6 V
- Allows down voltage translation
  - Inputs accept voltages to 5.5 V
- $I_{off}$  feature
  - Allows voltages on the inputs and outputs when  $V_{CC}$  is 0 V

## 9.4 Device Functional Modes

**Table 3. Function Table  
(Each 4-Bit Buffer)**

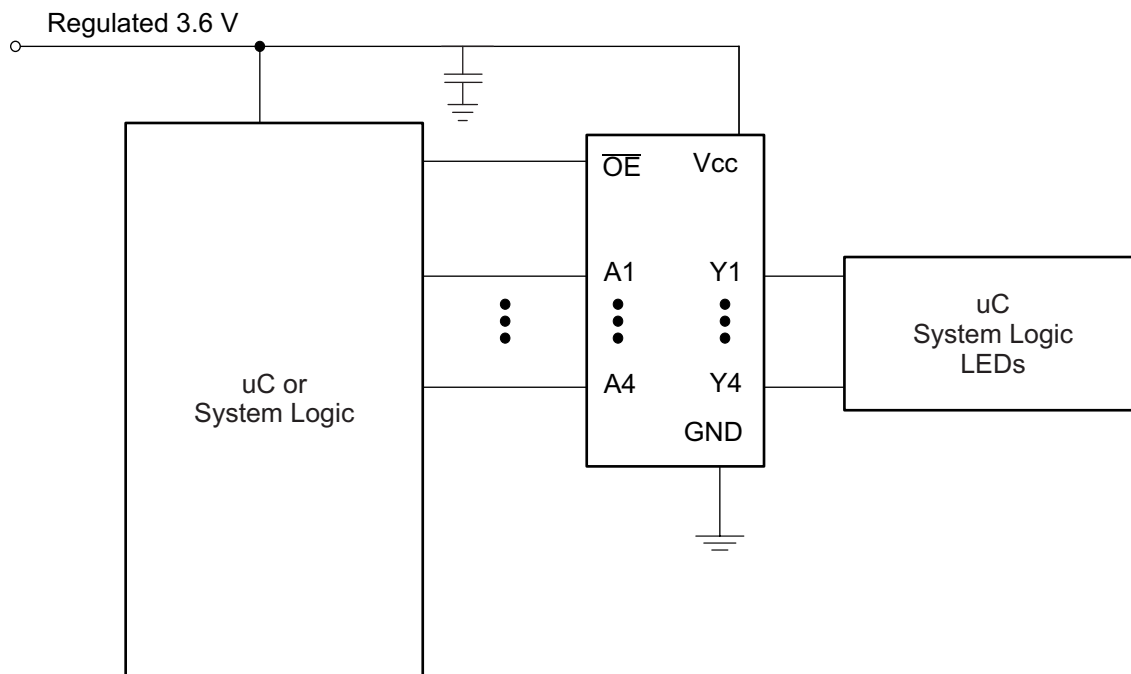
INPUTS		OUTPUT Y
$\overline{OE}$	A	
L	H	H
L	L	L
H	X	Z

## 10 Application and Implementation

### 10.1 Application Information

The SN74LVC162244A is a 16 bit buffer driver. This device can be used as four 4-bit, two 8-bit, or one 16-bit buffer. It allows data transmission from the A bus to the Y bus with 4 separate enable pins that control 4 bits each. The output-enable ( $\overline{OE}$ ) input can be used to disable sections of the device so the buses are effectively isolated. The device has 5.5 V tolerant inputs at any valid  $V_{CC}$  which allows it to be used in multi-power systems and can be used for down translation.

### 10.2 Typical Application



**Figure 4. Typical Application Schematic**

## Typical Application (continued)

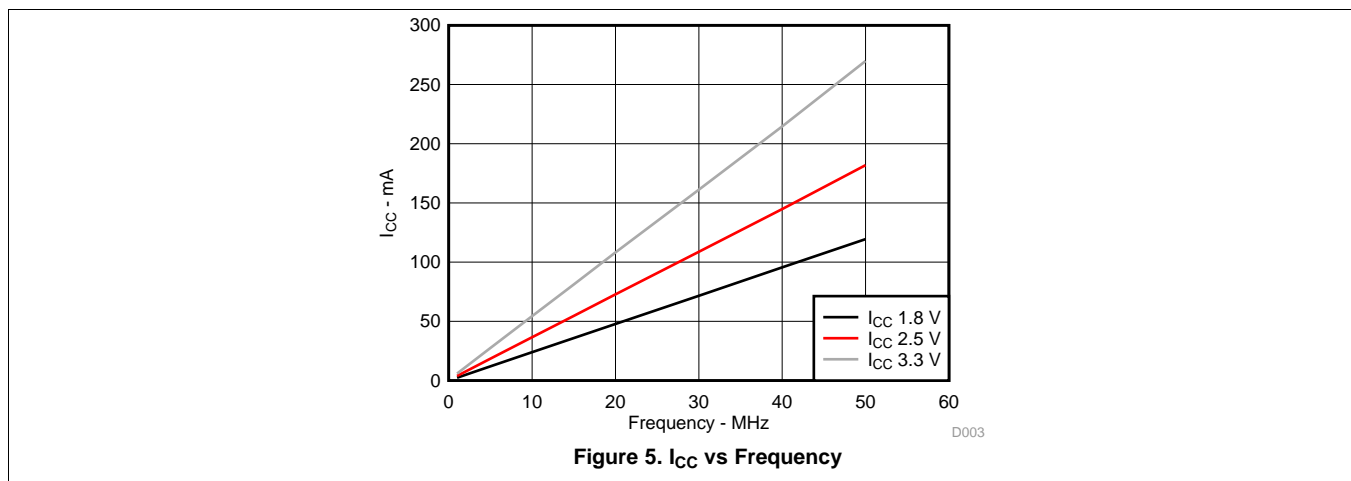
### 10.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads so routing and load conditions should be considered to prevent ringing.

### 10.2.2 Detailed Design Procedure

1. Recommended Input Conditions
  - Rise time and fall time specs: See ( $\Delta t/\Delta V$ ) in the [Recommended Operating Conditions](#) table.
  - Specified high and low levels: See ( $V_{IH}$  and  $V_{IL}$ ) in the [Recommended Operating Conditions](#) table.
  - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid  $V_{CC}$ .
2. Recommended Output Conditions
  - Load currents should not exceed 25 mA per output and 50 mA total for the part.
  - Outputs should not be pulled above  $V_{CC}$ .

### 10.2.3 Application Curves



## 11 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the [Recommended Operating Conditions](#) table.

Each  $V_{CC}$  pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1  $\mu\text{F}$  is recommended; if there are multiple  $V_{CC}$  pins, then 0.01  $\mu\text{F}$  or 0.022  $\mu\text{F}$  is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1  $\mu\text{F}$  and a 1  $\mu\text{F}$  are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

## 12 Layout

### 12.1 Layout Guidelines

When using multiple bit logic devices inputs should not ever float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Specified below are the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or  $V_{CC}$  whichever make more sense or is more convenient. It is generally OK to float outputs unless the part is a transceiver. If the transceiver has an output enable pin it will disable the outputs section of the part when asserted. This will not disable the input section of the IOs, so they also cannot float when disabled.

### 12.2 Layout Example

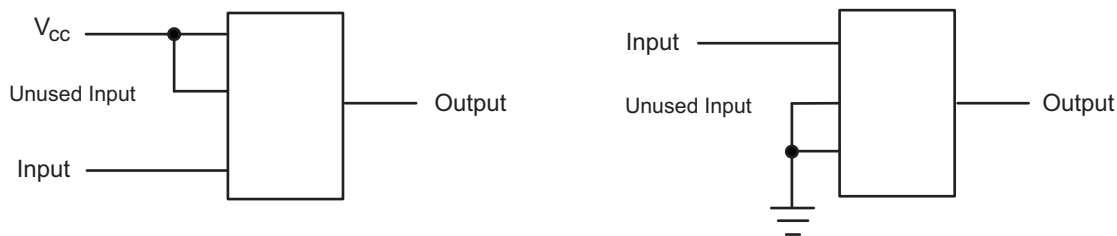


Figure 6. Layout Diagram

## 13 Device and Documentation Support

### 13.1 Trademarks

Widebus is a trademark of Texas Instruments.  
All other trademarks are the property of their respective owners.

### 13.2 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 13.3 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms and definitions.

## 14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
74LVC162244ADGGRG4	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC162244A	<a href="#">Samples</a>
SN74LVC162244ADGGR	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC162244A	<a href="#">Samples</a>
SN74LVC162244ADGVR	ACTIVE	TVSOP	DGV	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LD2244A	<a href="#">Samples</a>
SN74LVC162244ADL	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC162244A	<a href="#">Samples</a>
SN74LVC162244ADLR	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC162244A	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC162244ADGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74LVC162244ADGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74LVC162244ADLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC162244ADGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74LVC162244ADGVR	TVSOP	DGV	48	2000	356.0	356.0	35.0
SN74LVC162244ADLR	SSOP	DL	48	1000	367.0	367.0	55.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74LVC162244ADL	DL	SSOP	48	25	473.7	14.24	5110	7.87

# MECHANICAL DATA

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.

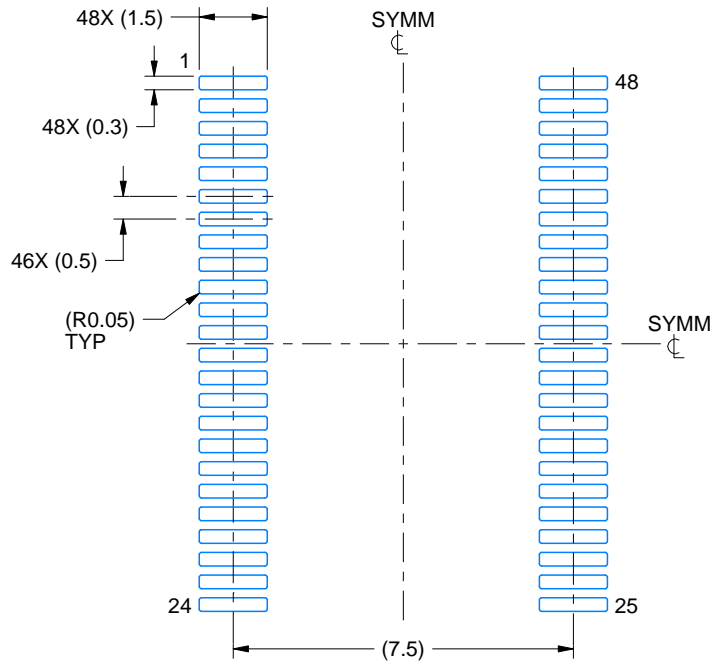


# EXAMPLE BOARD LAYOUT

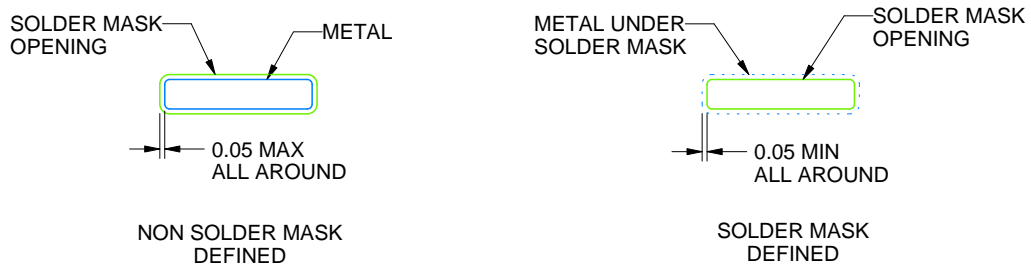
DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4214859/B 11/2020

NOTES: (continued)

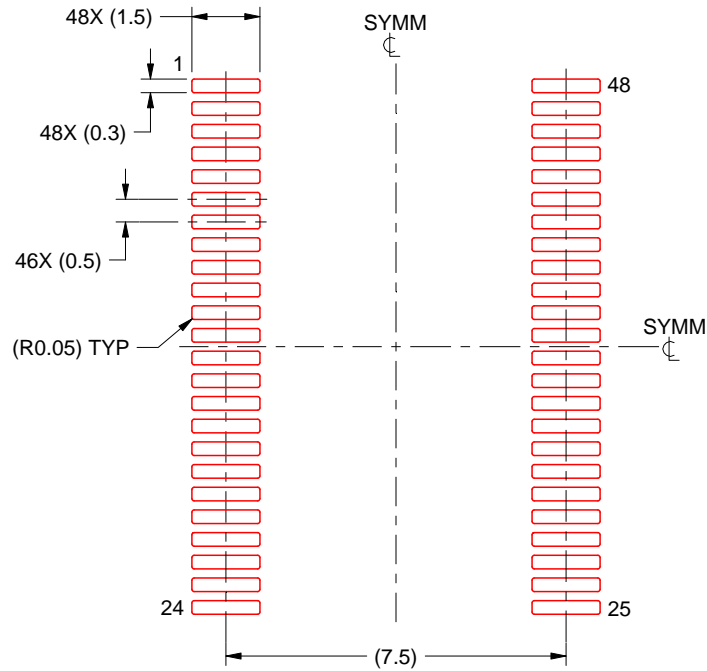
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4214859/B 11/2020

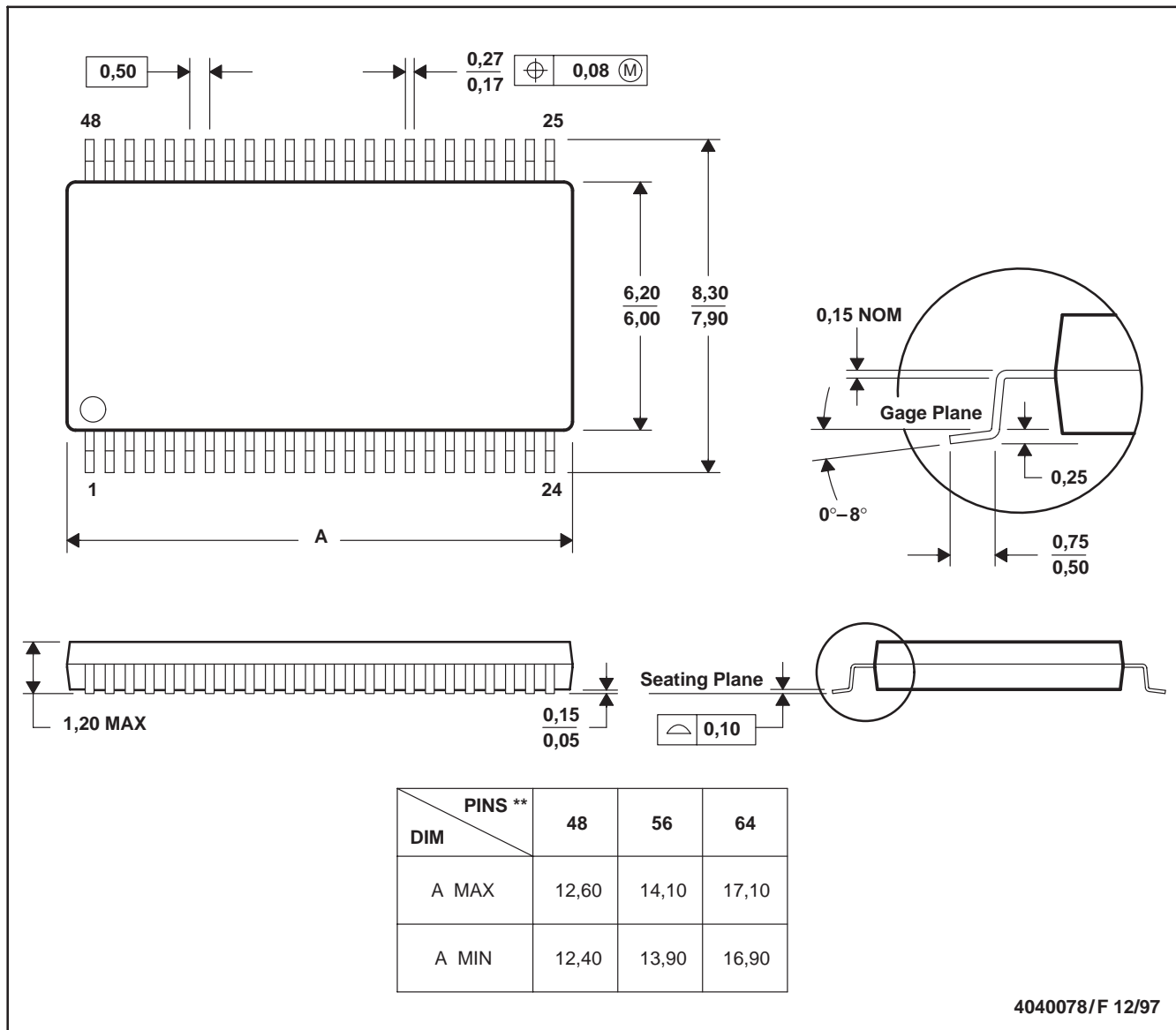
NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DGG (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153



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